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Docket No.: N0029.1650

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:  
Shinichi Miyazaki et al.

Application No.: 10/771,451

Confirmation No.: 3851

Filed: February 5, 2004

Art Unit: 2812

For: METHOD OF FORMING A  
CONNECTING CONDUCTOR AND  
WIRINGS OF A SEMICONDUCTOR CHIP

Examiner: L. A. Gurley

**RESPONSE TO ELECTION OF SPECIES REQUIREMENT**

U.S. Patent and Trademark Office  
220 20th Street S.  
Customer Window, Mail Stop Amendment  
Crystal Plaza Two, Lobby, Room 1B03  
Arlington, VA 22202

Dear Sir:

In response to the election requirement, Applicants hereby elect Species I covered by claim 1-7 with traverse.

Species I is, as asserted by the Examiner, directed to “a single resist post on connection pad” and Species II is directed to “first and second resist posts on connection pad and support member.” Office at 2. The Office Action asserts that no claim is generic. Applicants respectfully disagree. Claim 1 is generic as it reads on both the Species I and Species II embodiments.

Claim 1 reads on both Figures 2A through 2J and 7A through 7G. Figures 2A through 2J illustrate the Species I embodiments while Figure 7A through 7G illustrate the Species II embodiment. Claim 1 recites forming a resist post on a connection pad of a semiconductor chip. In both Figures 2D and 7A, resist post 204 is formed on connection pad 203 of semiconductor chip 205. Claim 1 further requires forming an insulating layer that covers the semiconductor chip and the resist post. In Figure 2E and Figure 7B, insulating layer 208 covers the semiconductor chip. Next, claim 1 recites removing a part of the insulating layer to expose a surface of the resist post. This is shown in both Figures 2F and 7C. Next, claim 1 recites removing the resist to form a through hole in the insulating layer, the through hole thereby exposing a connection pad. In Figures 2G and 7D through hole 209 forms the through hole in the insulating layer. Finally, claim 1 recites forming a wiring layer that is in electrical contact with the connection pad via the through hole and is elongated over the insulating layer. Wiring 211 is shown in both Figure 2H and 7E. As such, Applicants assert that claim 1 is generic to both the Species I and Species II embodiments and therefore respectfully traverse the restriction.

Applicants' election is made without prejudice. As noted by the Examiner, upon the allowance of a generic claim, Applicants will be entitled to consideration of claims to not more than two species in addition to the elected species, provided that all claims to each additional species are written in dependent form or otherwise include all the limitations of an allowed generic claim as provided by 37 CFR 1.146.

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An action on the merits of all the claims and a Notice of Allowance thereof are respectfully requested.

Dated: March 16, 2005

Respectfully submitted,

By 

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